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US2006191798A1 Electrolytic copper foil with low roughness surface and process for producing the same

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Abstract

An electrolytic copper foil with low roughness surface whose surface roughness (Rz) is 2.0 μm or less, the surface uniformly provided with low roughness without uneven surge, which electrolytic copper foil exhibits a percent elongation of 10.0% or higher at 180° C. This electrolytic copper foil with low roughness surface can be obtained by a process for producing an electrolytic copper foil, comprising passing a direct current between an insoluble anode consisting of a titanium plate coated with a Platinum Group element or oxide thereof and a titanium drum as a cathode counter to the anode in an electrolyte of an aqueous solution of sulfuric acid/copper sulfate, wherein the electrolyte contains an oxyethylene surfactant a polyethyleneimine or derivative thereof, a sulfonate of active organosulfur compound and chloride ions.